



#4/A  
7/16/02 2812  
MCM/SL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Michael E. Connell and Tongbi Jiang

**Serial No.:** 10/082,372

**Filed:** February 25, 2002

**For:** WAFER BACK SIDE COATING TO  
BALANCE STRESS FROM PASSIVATION  
LAYER ON FRONT OF WAFER AND BE  
USED AS A DIE ATTACH ADHESIVE

**Examiner:** Unknown

**Group Art Unit:** 2812

**Attorney Docket No.:** 5083US (01-0428)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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**PRELIMINARY AMENDMENT**

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.